

GS138K

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	50V
RDS(ON)	2Ω
ID	640mA

Description

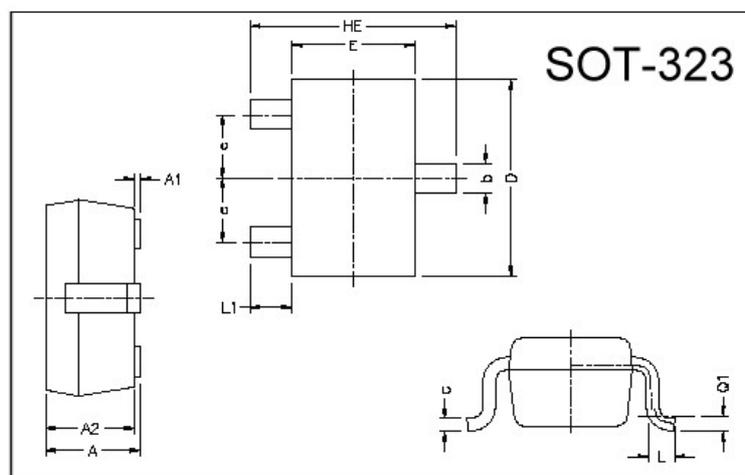
The GS138K utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The GS138K is universally used for all commercial-industrial applications.

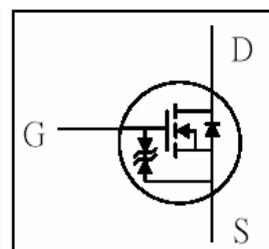
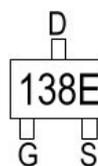
Features

- *Simple Drive Requirement
- *Small Package Outline
- *RoHS Compliant

Package Dimensions



Marking :



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	0.80	1.10	L1	0.42 REF.	
A1	0	0.10	L	0.15	0.35
A2	0.80	1.00	b	0.25	0.40
D	1.80	2.20	c	0.10	0.25
E	1.15	1.35	e	0.65 REF.	
HE	1.80	2.40	Q1	0.15 BSC.	

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	50	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current ³ , $V_{GS}@10V$	$I_D @TA=25^{\circ}C$	640	mA
Continuous Drain Current ³ , $V_{GS}@10V$	$I_D @TA=70^{\circ}C$	500	mA
Pulsed Drain Current ^{1,2}	I_{DM}	950	mA
Power Dissipation	$P_D @TA=25^{\circ}C$	0.35	W
Linear Derating Factor		0.003	W/°C
Operating Junction and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Ratings	Unit
Thermal Resistance Junction-ambient ³ Max.	R_{thj-a}	360	°C/W

Electrical Characteristics(Tj = 25°C Unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	50	-	-	V	$V_{GS}=0, I_D=250\mu A$
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS} / \Delta T_j$	-	0.06	-	V/°C	Reference to 25°C, $I_D=1mA$
Gate Threshold Voltage	$V_{GS(th)}$	0.5	-	2.0	V	$V_{DS}=V_{GS}, I_D=1mA$
Forward Transconductance	g_{fs}	-	600	-	mS	$V_{DS}=10V, I_D=600mA$
Gate-Source Leakage Current	I_{GSS}	-	-	±10	uA	$V_{GS}= \pm 20V$
Drain-Source Leakage Current(Tj=25°C)	I_{DSS}	-	-	1	uA	$V_{DS}=50V, V_{GS}=0$
Drain-Source Leakage Current(Tj=70°C)		-	-	100	uA	$V_{DS}=40V, V_{GS}=0$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	2	Ω	$V_{GS}=10V, I_D=500mA$
		-	-	4		$V_{GS}=4.5V, I_D=400mA$
Total Gate Charge ²	Q_g	-	1	1.6	nC	$I_D=600mA$ $V_{DS}=50V$ $V_{GS}=4.5V$
Gate-Source Charge	Q_{gs}	-	0.5	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	0.5	-		
Turn-on Delay Time ²	$T_{d(on)}$	-	12	-	ns	$V_{DS}=30V$ $I_D=600mA$ $V_{GS}=10V$ $R_G=3.3\Omega$ $R_D=52\Omega$
Rise Time	T_r	-	10	-		
Turn-off Delay Time	$T_{d(off)}$	-	56	-		
Fall Time	T_f	-	29	-		
Input Capacitance	C_{iss}	-	32	50	pF	$V_{GS}=0V$ $V_{DS}=25V$ $f=1.0MHz$
Output Capacitance	C_{oss}	-	8	-		
Reverse Transfer Capacitance	C_{rss}	-	6	-		

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage ²	V_{SD}	-	-	1.2	V	$I_S=200mA, V_{GS}=0V$

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

3. Surface mounted on FR4 board, $t \leq 10sec$.

Characteristics Curve

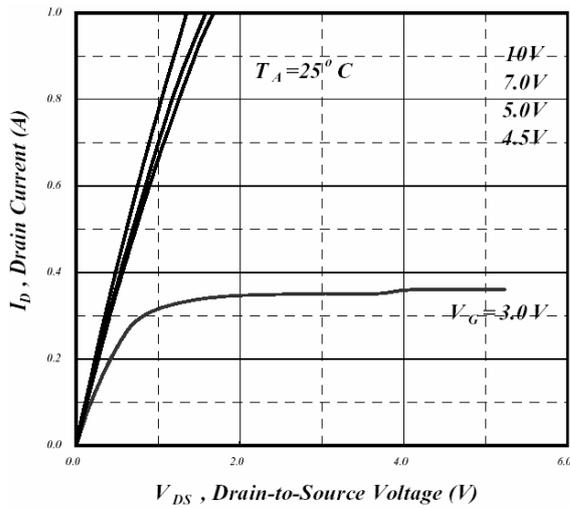


Fig 1. Typical Output Characteristics

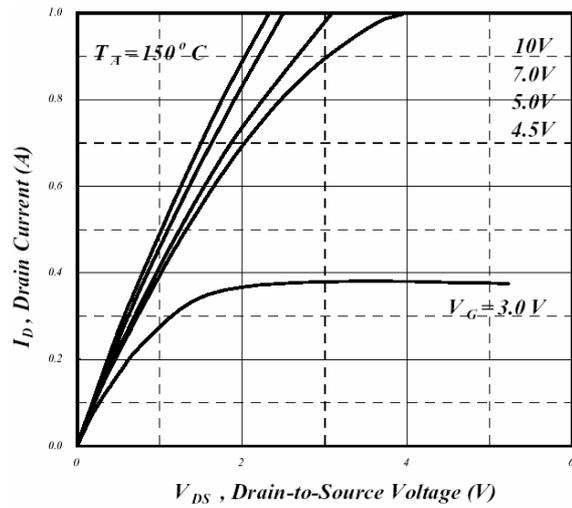


Fig 2. Typical Output Characteristics

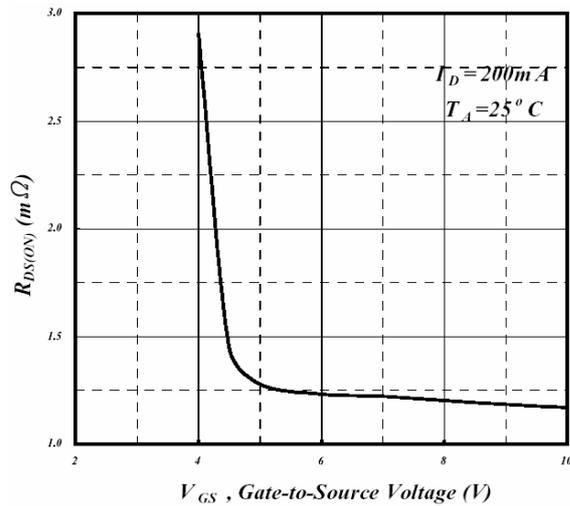


Fig 3. On-Resistance v.s. Gate Voltage

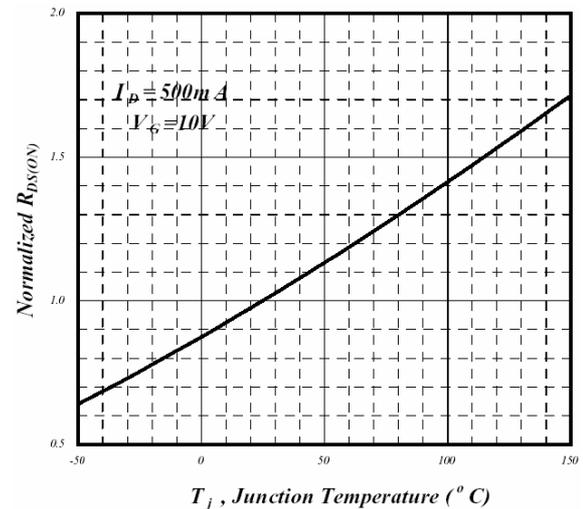


Fig 4. Normalized On-Resistance v.s. Junction Temperature

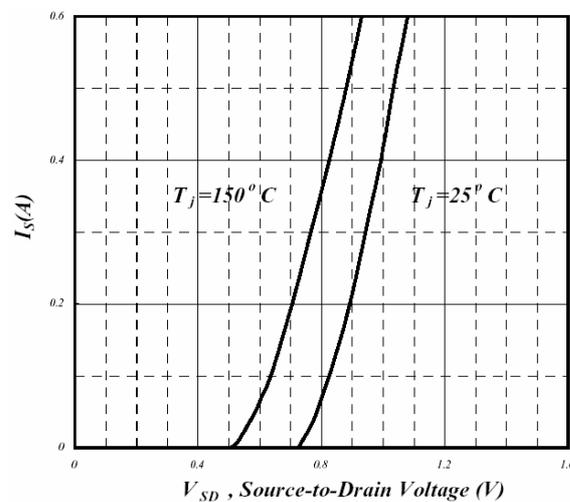


Fig 5. Forward Characteristics of Reverse Diode

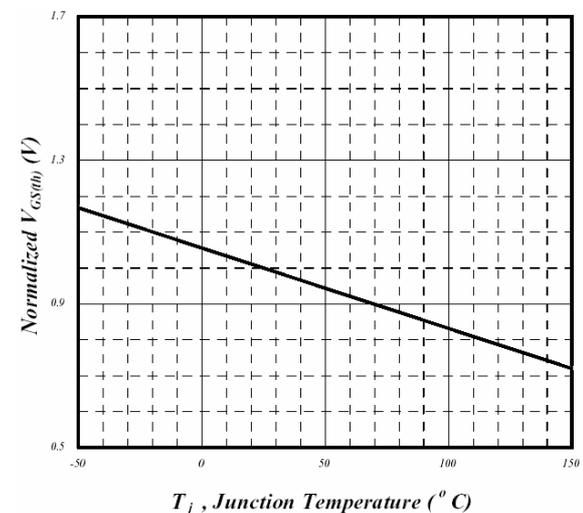


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

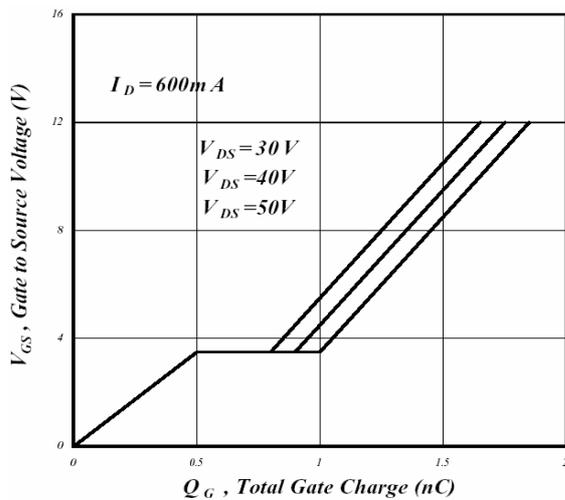


Fig 7. Gate Charge Characteristics

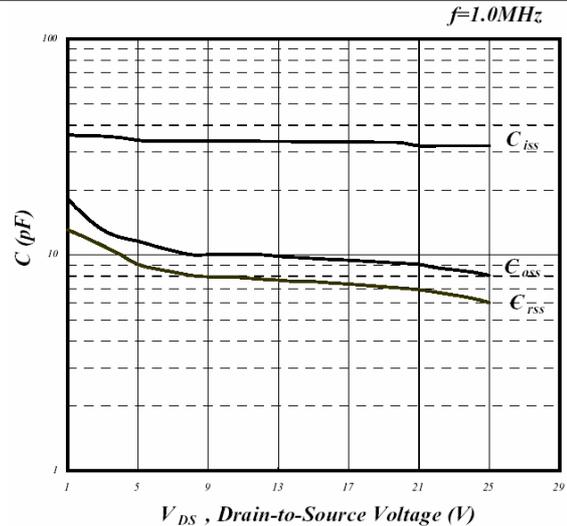


Fig 8. Typical Capacitance Characteristics

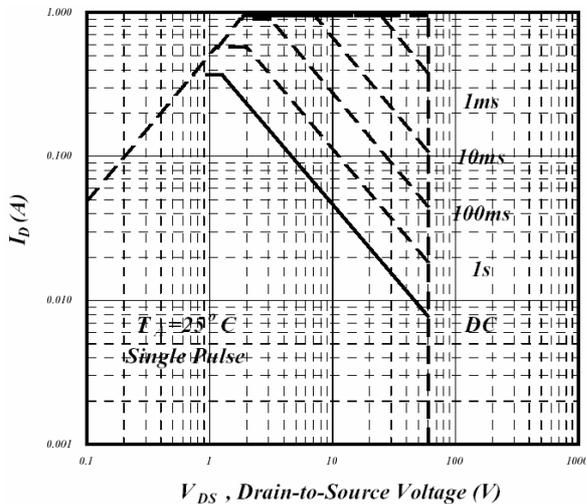


Fig 9. Maximum Safe Operating Area

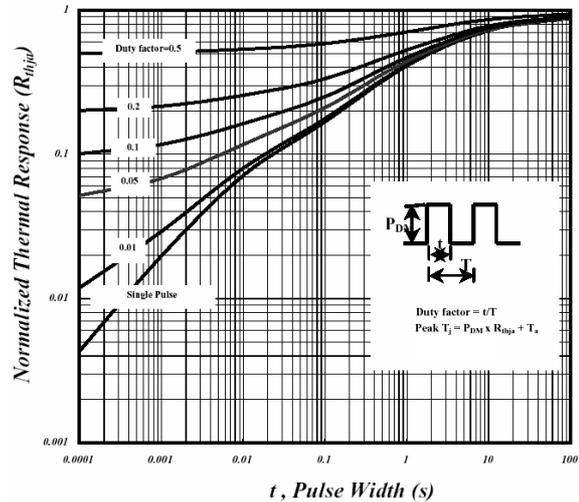


Fig 10. Effective Transient Thermal Impedance

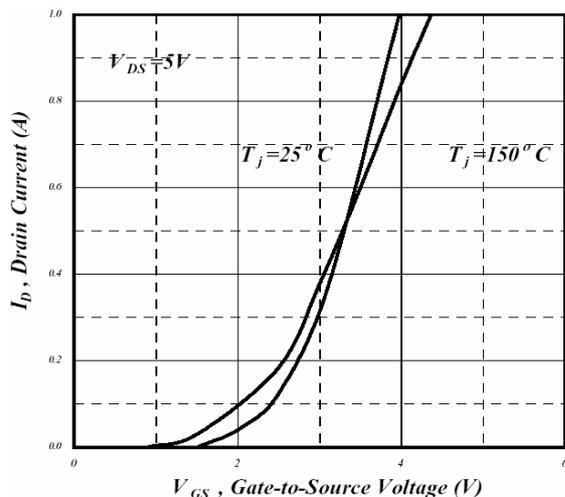


Fig 11. Transfer Characteristics

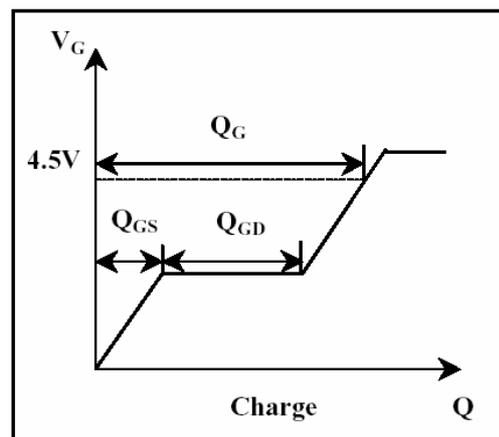


Fig 12. Gate Charge Waveform

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